ABBOCIATION CONNECTING ELECTRONICE INDUSTRIES® INCLUSTRIES®	burn, Illinois, Al	ll rights reserved utions.	under both	This docume level parts, t	ent is a declaration en declaration	on of the sub compasses	bstances v all lower	within the manufactu level materials for w	rer listed i hich the r	tem. Note: nanufacture	if the item is an as r has engineering	sembly with lower responsibility.
IPC Web Site for Information on http://www.ipc.org/IPC-175x	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute			*	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information					tion		
Supplier Information												
Company name*	Dany name* Company unique ID			Unique ID Authority				Response Date*				
onsemi									2023-06-08			
Contact Name	Title - Contact]	Phone - Contact*				Email - Contact*			
Product-Env-Stewards	Product Enviro Compliance				NA			Product-Env-Stewards@onsemi.com				
Authorized Representative*	I Representative* Title - Representative]	Phone - Representative*				Email - Representative*			
Product-Env-Stewards Product Enviro Compliance					NA				Product-Env-Stewards@onsemi.com			
Requester Item Number Mfr Iter	n Number	Mfr Item Name			Effective Date Ve		Μ	Manufacturing Site		Weight*	UOM	Unit Type
MC74H 2G	C74HC4067ADWR IC MUX/DEMUX		X 1X16	X16 2			P	PH1		661.78	mg	Each
Manufacturing Proccess Information												
Terminal Plating / Grid Array Material	Ferminal Base Alloy J-S		J-STD-020 MSL	Rating	Peak Process Body Tempe		mperature	ture Max Time at Peak Te		ture Num	ber of Reflow Cyc	les
Matte Tin (Sn) - annealed	Tin (Sn) - annealed CU Alloy		3	260		С		30 seco		seconds 3		
Comments												
ATTENTION: MSL 3 Rated item requires Bake and I	Dry Pack (after	electrical test)										
For more information regarding material composition	please refer to	page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		nium (Cr6+), Polybro	ominated Biphenyls (PBB), Polybron	dmium and quantity limit of 0.1% by mass (100 minated Diphenyl Ethers (PBDE), and Bis(2-eth	
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	on above	Supplier Acceptance	* Accepted	
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the
Supplier Digital Signature Ra	stislav Drska	Le			

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	3.79	mg	Supplier	Silicon (Si)	7440-21-3		3.79	mg
Die Attach 24	24.58	mg	Supplier	Silver (Ag)	7440-22-4		18.435	mg
			Supplier	Epoxy resins	129915-35-1		6.145	mg
Lead Frame 385.08	385.08	mg	Supplier	Silver (Ag)	7440-22-4		2.6956	mg
			Supplier	Zinc (Zn)	7440-66-6		0.4621	mg
			Supplier	Iron (Fe)	7439-89-6		9.0494	mg
			Supplier	Copper (Cu)	7440-50-8		372.7574	mg
			Supplier	Phosphorus (P)	7723-14-0		0.1155	mg
Mold Compound-Black	242.16	mg		Epoxy Phenol Resin	proprietary data		25.4268	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		216.7332	mg
Plating	5.6	mg	Supplier	Tin (Sn)	7440-31-5		5.6	mg
Wire Bond - Cu	0.57	mg	Supplier	Copper (Cu)	7440-50-8		0.57	mg